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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/573,492 05/15/2006		Koichi Naniwae	8074-1143	9283	
466 YOUNG & TH	7590 06/09/201 OMPSON	EXAMINER			
209 Madison St Suite 500	reet	JONES, ERIC W			
Alexandria, VA	. 22314	ART UNIT	PAPER NUMBER		
			2892		
			NOTIFICATION DATE	DELIVERY MODE	
			06/09/2010	ELECTRONIC	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

DocketingDept@young-thompson.com

Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)		
10/573,492	NANIWAE, KOICHI		
Examiner	Art Unit		
ERIC W. JONES	2892		

	ERIC W. JONES	2892				
The MAILING DATE of this communication appe	ars on the cover sheet with the c	correspondence add	ress			
THE REPLY FILED <u>19 May 2010</u> FAILS TO PLACE THIS APPI	LICATION IN CONDITION FOR AL	LOWANCE.				
1. The reply was filed after a final rejection, but prior to or on application, applicant must timely file one of the following application in condition for allowance; (2) a Notice of Apperfor Continued Examination (RCE) in compliance with 37 C periods:	replies: (1) an amendment, affidavi eal (with appeal fee) in compliance	t, or other evidence, w with 37 CFR 41.31; or	which places the r (3) a Request			
a) The period for reply expires <u>3</u> months from the mailing date						
b) The period for reply expires on: (1) the mailing date of this Anno event, however, will the statutory period for reply expire la Examiner Note: If box 1 is checked, check either box (a) or (MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f	ater than SIX MONTHS from the mailing b). ONLY CHECK BOX (b) WHEN THE	g date of the final rejection	on.			
extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee ave been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee nder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as et forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, hay reduce any earned patent term adjustment. See 37 CFR 1.704(b). NOTICE OF APPEAL						
The Notice of Appeal was filed on A brief in compliance with 37 CFR 41.37 must be filed within two months of the date of filing the Notice of Appeal (37 CFR 41.37(a)), or any extension thereof (37 CFR 41.37(e)), to avoid dismissal of the appeal. Since a Notice of Appeal has been filed, any reply must be filed within the time period set forth in 37 CFR 41.37(a).						
AMENDMENTS						
 The proposed amendment(s) filed after a final rejection, be (a) They raise new issues that would require further cor (b) They raise the issue of new matter (see NOTE belowed) 	nsideration and/or search (see NOTw);	TE below);				
(c) ☐ They are not deemed to place the application in beti appeal; and/or	er form for appeal by materially rec	ducing or simplifying tl	ne issues for			
(d) ☐ They present additional claims without canceling a c	corresponding number of finally reje	ected claims.				
NOTE: (See 37 CFR 1.116 and 41.33(a)).						
 The amendments are not in compliance with 37 CFR 1.12 Applicant's reply has overcome the following rejection(s): 		mpliant Amendment (l	PTOL-324).			
6. Newly proposed or amended claim(s) would be all non-allowable claim(s).		imely filed amendmer	nt canceling the			
7. For purposes of appeal, the proposed amendment(s): a) [how the new or amended claims would be rejected is prov The status of the claim(s) is (or will be) as follows:		l be entered and an e	xplanation of			
Claim(s) allowed: Claim(s) objected to:						
Claim(s) rejected: <u>3-7, 9, 11-18, 21-25, 27, 29-38 and 49-</u> Claim(s) withdrawn from consideration:	<u>57</u> .					
AFFIDAVIT OR OTHER EVIDENCE	- la - f - m - m - m - tha - d - ta - a f - f : library - N					
 The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e). 						
The affidavit or other evidence filed after the date of filing a Notice of Appeal, but prior to the date of filing a brief, will <u>not</u> be entered because the affidavit or other evidence failed to overcome <u>all</u> rejections under appeal and/or appellant fails to provide a showing a good and sufficient reasons why it is necessary and was not earlier presented. See 37 CFR 41.33(d)(1).						
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER	n of the status of the claims after er	ntry is below or attach	ed.			
11. ☑ The request for reconsideration has been considered but does NOT place the application in condition for allowance because: See Continuation Sheet.						
12. Note the attached Information <i>Disclosure Statement</i> (s). (13. Other:	PTO/SB/08) Paper No(s)					
/Thao X Le/	/ERIC W JONES/					
Supervisory Patent Examiner, Art Unit 2892	Examiner, Art Unit 2892 6/3/2010					

Continuation of 11. does NOT place the application in condition for allowance because: In Re applicant's argument(s) that Chiu et al (5,407,531) would not satisfy the claimed relationship of IRI<Ir2I<Ir1I by either anticipation or obviousness, the examiner, respectfully, disagrees based the following:

- 1. Chiu et al disclose various gas flow conditions which either:
 - a. etch the semiconductor layer with etch gas(es) soley.
 - b. etch the semiconductor layer with both etch and growth gases simultaneously or
 - c. grow a semiconductor layer.

In case a, which would represent r 1, the highest etch rate of 0.1 to 3 micrometers per hour (0.0278 to 0.83 nanometers per second) is achieved. In case b, which would represent r 1 + r 2, the overall etch rate due to r 1 alone is reduced since the r 2 growth gas component is flowed at a rate of upto 40% of the gas flow rate of the r 1 gas component. Further, Chiu et al disclose that the function of the r 2 gas component is introduced to smooth the etch of the r 1 gas component by filling in etch pits created by the r 1 gas etching. The leads to the effect of reducing the overall etch rate of 0.0278 to 0.83 nm/sec due to r 1 gas etching alone.

Based on this evidence, it can be argued through either anticipation or obviousness that since the overall rate of change R of the semiconductor layer is negative, which means the final layer thickness is reduced due to the overall effect of etching whether case a exists where etching is due soley to etch gas(es) or case b, where etching is due to both etch and growth gases.

Quantatively, rate of change R equals etch rate r 1 due to etch gases alone yield etch rates of 0.0278 to 0.83 nm/sec; rate of change R equals etch rate r 1 + r 2 due to both etch and growth gases would yield a rate less than the 0.0278 to 0.83 nm/sec range achieved by etch gas(es) alone since it has been pointed out that the growth gas component inhibits etching by filling etch pits to smooth the overall etch. See Chiu et al column 3, lines 3-19; 41-60 and column 5, lines 43-55

Since the flow of the growth gas component is flowed at only upto 40% of the etch gas flow component and the overall rate of change R of the semiconductor layer is negative (layer thickness reduced), the r 2 growth rate can either be anticipated to be or is obviously less than the 0.0278 to 0.83 nm/sec range achieved by etch gas(es) alone. See Chiu et al column 3, lines 3-19; 41-60 and column 5, lines 43-55

For example, if r 1 has an etch rate of 0.0278 nm/sec, r 2 is anticipated to be or is obviously upto but less than 0.0278 nm/sec for the overall rate of change R to be negative (layer thickness reduced). Therefore, r < 1 Likewise, if r 1 has an etch rate of 0.83 nm/sec, r 2 is anticipated to be or is obviously upto but less than 0.83 nm/sec for the overall rate of change R to be negative.

Therefore, Chiu et al disclose the conditions under which the claimed relationship of IRI<Ir2I<Ir1I is satisfied by either anticipation or obviousness.

It should also be noted that either a prima facie case of either anticipation or obviousness has been established since Chiu et al disclose a substantially identical process(es) to the applicant's claimed and specification disclosed process(es). Therefore, one would expect similar results as the claimed results such as the relationship of I R I < I r 2 I < I r 1 I. See MPEP 2112.02.

Based on the above responses to the applicant's arguments, it is deemed the 35 USC 102 and 35 USC 103 rejections of the claims to Chiu et al are proper. Thus, all current Final Rejections (claims 3-7, 9, 11-18, 21-25, 27, 29-38 and 49-57) to Chiu et al are maintained.

It should be noted that the applicant's argument(s) with respect to Koichi JP2003-282455 are persuasive. Therefore, ALL Final Rejections to Koichi only are withdrawn.